

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJBB7002K
Package Type :	DFN1006-3L-A

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100%	8.60%
Lead Frame	CU	7440-50-8	94.62%	40.76%
	Fe	7439-89-6	0.20%	
	Si	7440-21-3	0.73%	
	Mn	7439-96-5	0.10%	
	Ni	7440-02-0	3.20%	
	Zn	7440-66-6	1%	
	Pb	7439-92-1	0.005%	
	Mg	7439-95-4	0.15%	
Soft Solder	Sliver	7440-22-4	80.42%	0.89%
	Epoxy Resin	24969-06-0	12.05%	
	1,4Bisbutane	2425-79-8	5.21%	
	Poly-p-phenylene diamine terephthalamide fiber	/	2.32%	
Wire	Copper	7440-50-8	97.50%	6.08%
	Palladium	7440/5/3	2.50%	
Mold Compound	Epoxy resin A	Secret	6.50%	39.82%
	Epoxy resin B	Secret	0.55%	
	Phenol Resin	Secret	3%	
	Silica(Amorphous) A	60676-86-0	80%	
	Silica(Amorphous) B	7631-86-9	6.50%	
	Metal Hydroxide	Secret	3%	
	Carbon black	1333-86-4	0.45%	
Plating	Tin	7440-31-5	100%	3.85%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.